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FCPF600N60ZL1

N-Channel SuperFET[®] II MOSFET 600 V, 7.4 A, 600 m Ω

Features

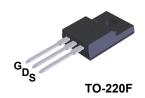
- 650 V @ T_{.1} = 150°C
- Typ. $R_{DS(on)}$ = 510 $m\Omega$
- Ultra Low Gate Charge (Typ. Q_q = 20 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 74 pF)
- 100% Avalanche Tested
- · ESD Improved Capacity
- RoHS Compliant

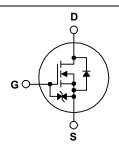
Applications

- · LCD / LED TV and Lightning
- Adapter
- · AC-DC Power Supply

Description

SuperFET® II MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCPF600N60ZL1	Unit
V _{DSS}	Drain to Source Voltage			600	V
\/	Cata to Source Voltage	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V
1	Drain Current	- Continuous (T _C = 25°C)		7.4*	Α
I _D	Diam Current	- Continuous (T _C = 100°C)		4.7*	_ A
I_{DM}	Drain Current	- Pulsed	(Note 1)	22.2*	Α
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	135	mJ
I _{AR}	Avalanche Current		(Note 1)	1.5	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	0.89	mJ
	MOSFET dv/dt			100	\//no
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
Б	Device Dissipation	(T _C = 25°C)		28	W
P_{D}	Power Dissipation - Derate Above 25°C			0.22	W/°C
T _J , T _{STG}	Operating and Storage Temperatu	re Range		-55 to +150	οС
TL	Maximum Lead Temperature for S	oldering, 1/8" from Case for 5 Se	econds	300	οС

^{*}Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FCPF600N60ZL1	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	4.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	*C/vv

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF600N60ZL1	FCPF600N60Z	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit		
Off Characteristics								
D\/	Drain to Source Presidents Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 10 \text{ mA, T}_{J} = 25^{\circ}\text{C}$	600	-	-	V		
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	650	-	-	, v		
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.67	-	V/°C		
BV _{DS}	Drain to Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 7.4 A	-	700	-	V		
_	Zara Cata Valtaga Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1			
^I DSS	Zero Gate Voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	1.32	-	μА		
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	uA		

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$	-	0.51	0.6	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 3.7 \text{ A}$	-	6.7	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 05.V V 0.V	-	840	1120	pF
C _{oss}	Output Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	630	840	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	-	30	45	pF
C _{oss}	Output Capacitance	V _{DS} = 380 V, V _{GS} = 0 V, f = 1 MHz	-	16.5	-	pF
C _{oss(eff.)}	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	74	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 3.7 A,	-	20	26	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	3.4	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	7.5	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	2.89	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	13	36	ns
t _r	Turn-On Rise Time	$V_{DD} = 380 \text{ V, } I_{D} = 3.7 \text{ A,}$		-	7	24	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω		-	39	88	ns
t_{f}	Turn-Off Fall Time	((Note 4)	-	9	28	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	7.4	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	22.2	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 3.7 A		-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 3.7 A,	-	200	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	2.3	-	μС

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I $_{AS}$ = 1.5 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C.
- 3. I $_{SD} \leq 3.7$ A, di/dt ≤ 200 A/µs, V $_{DD} \leq BV_{DSS},$ starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

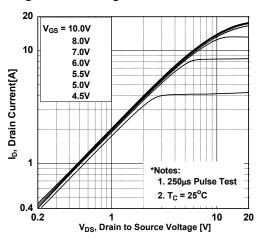


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

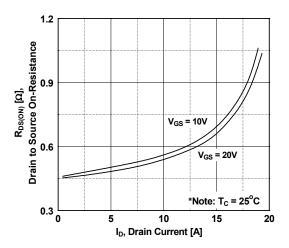


Figure 5. Capacitance Characteristics

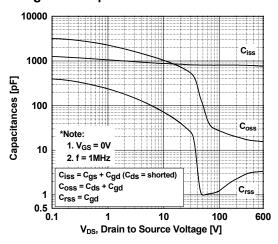


Figure 2. Transfer Characteristics

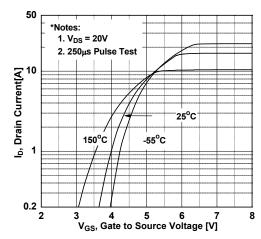


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

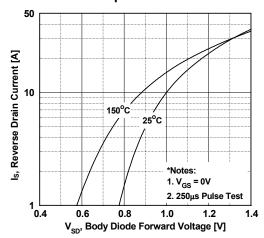
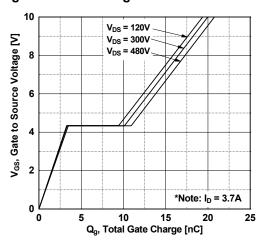


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

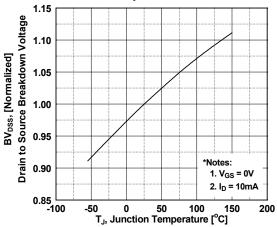


Figure 9. Maximum Safe Operating Area

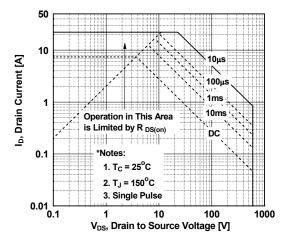


Figure 11. Eoss vs. Drain to Source Voltage

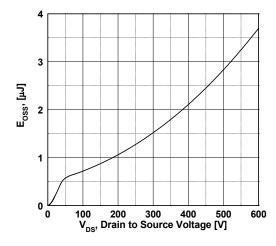


Figure 8. On-Resistance Variation vs. Temperature

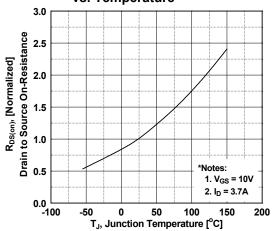
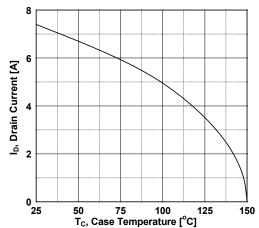
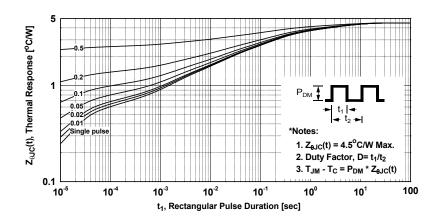


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



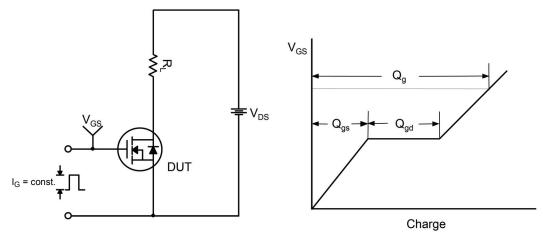


Figure 13. Gate Charge Test Circuit & Waveform

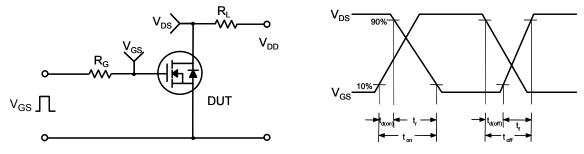


Figure 14. Resistive Switching Test Circuit & Waveforms

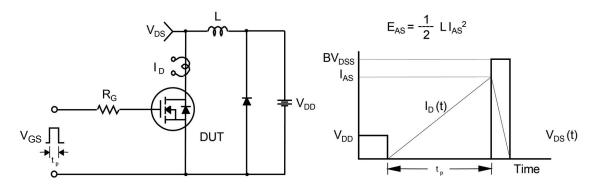
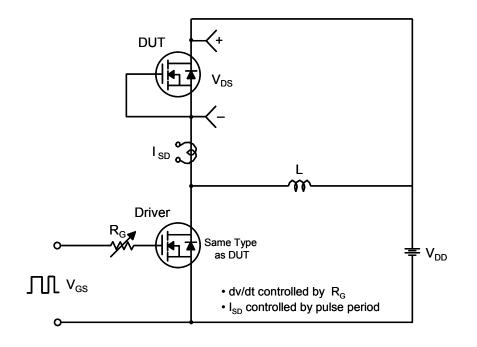


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



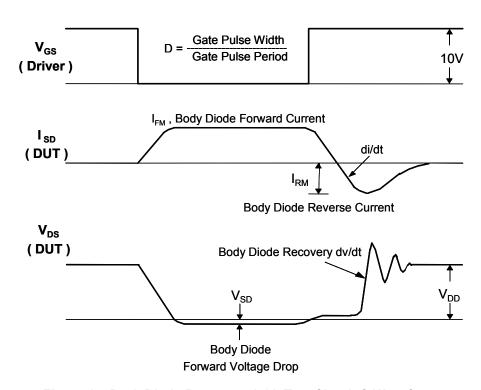
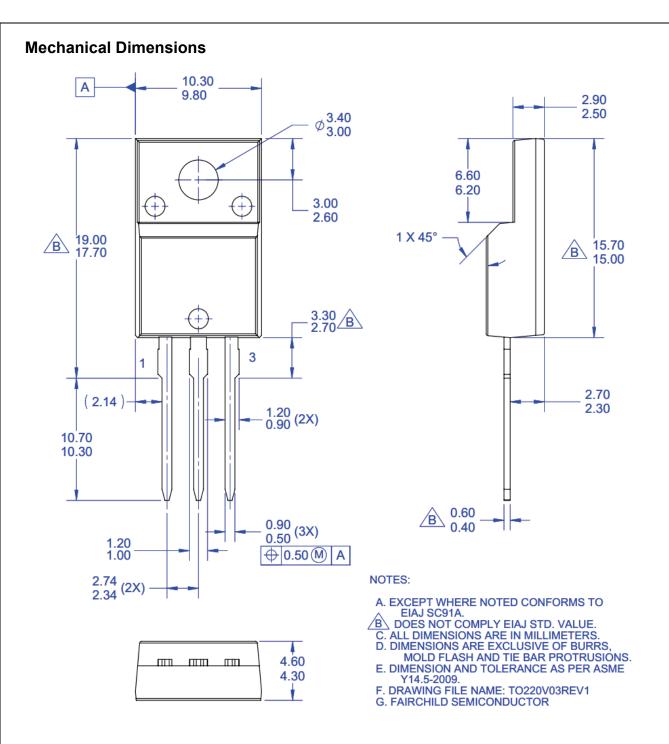


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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